SECTION I—SPECIFICATION AMENDMENTS

Please replace the specified paragraphs in the specification with the amended paragraphs shown in marked-up form below:

1.   Please replace the paragraph beginning at page 5, line 25, with the following amended paragraph:

Figure 3A illustrates an embodiment of an encapsulated wire-bonded die 300. As with the encapsulated dies 200 and 250, the encapsulated die 300 comprises a die 304 bonded to a substrate 302 using a layer of adhesive 306. In one embodiment the die 304 comprises an integrated circuit, but in other embodiments it may be something different such as an optical die, microelectromechanical system (MEMS) die, etc. The die is connected to the substrate by a plurality of wires 308, and a mold cap 301 is placed over the die and wires. Like the mold cap 201, the mold cap 301 includes an electrically insulating portion 310 and a thermally conductive portion 312. The mold cap 301, however, has a different construction than the mold cap 201. In the mold cap 301, the electrically insulating portion 310 is positioned only around the perimeter of the die 304, such that it still encapsulates the wires 308 but only partially encapsulates the die 304. In other words, the electrically insulating portion 310 covers the wires but is only in contact with the sides 303 and a small portion near the perimeter of the top 305 of the die. Once the electrically insulating portion 310 is in place, the thermally conductive portion 312 is overmolded on top of the die and the electrically insulating portion. Once in place, the thermally conductive portion is in direct contact with a large portion of the top surface 305 of the die. This direct contact between the thermally conductive portion and the die means that the mold cap 301 has greatly enhanced heat transfer compared ~~tot he~~ to the mold cap 201, since thermal energy from large portions of the die 314 is more quickly transferred through the mold cap because it no longer has to cross an electrically insulating (and therefore thermally insulating) portion.

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